



RELIABILITY REPORT
FOR
MAX5025EUT+
PLASTIC ENCAPSULATED DEVICES

October 5, 2009

MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX5025EUT+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX5025-MAX5028 constant-frequency, pulse-width modulating (PWM), low-noise boost converters are intended for low-voltage systems that often need a locally generated high voltage. These devices are capable of generating low-noise, high output voltages required for varactor diode biasing in TV tuners, set-top boxes, and PCI cable modems. The MAX5025-MAX5028 operate from as low as 3V and switch at 500kHz. The constant-frequency, current-mode PWM architecture provides for low output noise that is easy to filter. A 40V lateral DMOS device is used as the internal power switch, making the devices ideal for boost converters up to 36V. The MAX5025/MAX5026 adjustable versions require the use of external feedback resistors to set the output voltage. The MAX5027/MAX5028 offer a fixed 30V output. These devices are available in a small, 6-pin SOT23 package.

II. Manufacturing Information

A. Description/Function:	500kHz, 36V Output, SOT23, PWM Step-Up DC-DC Converters
B. Process:	BCD8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Thailand
F. Date of Initial Production:	October 27, 2001

III. Packaging Information

A. Package Type:	6-pin SOT23
B. Lead Frame:	Copper Alloy
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1301-0024
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	115°C/W
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	74.6°C/W
M. Multi Layer Theta Jc:	6.1°C/W

IV. Die Information

A. Dimensions:	60 X 41 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 72 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 14.9 \times 10^{-9}$$

$$\lambda = 14.9 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the BCD8 Process results in a FIT Rate of 0.06 @ 25C and 1.08 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The NP15 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX5025EUT+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	72	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data